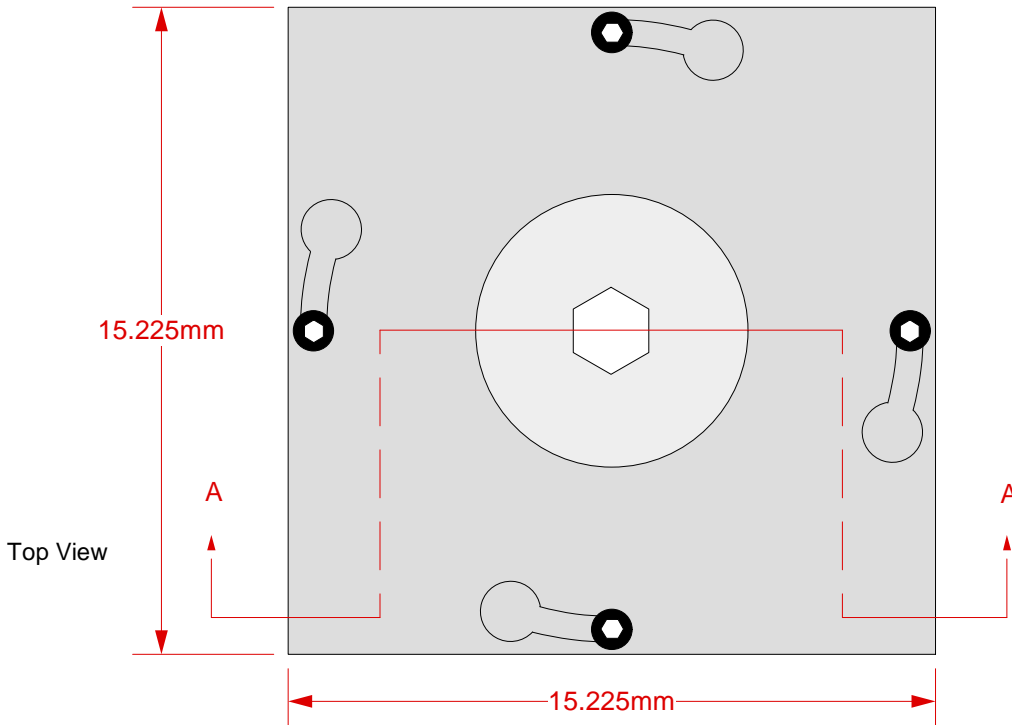


GHz BGA Socket - Direct mount, solderless

Features

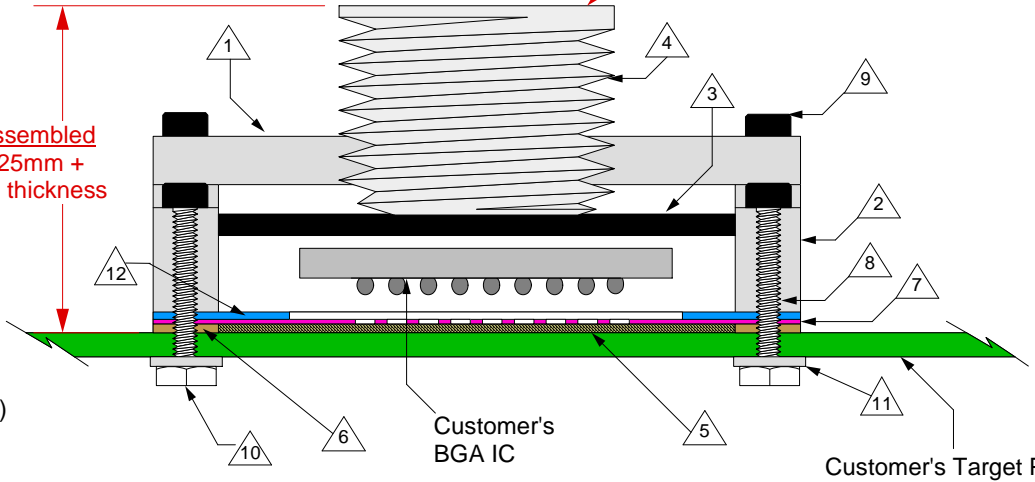
- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid




Top View

Assembled
8.25mm +
IC thickness

Side View
(Section AA)



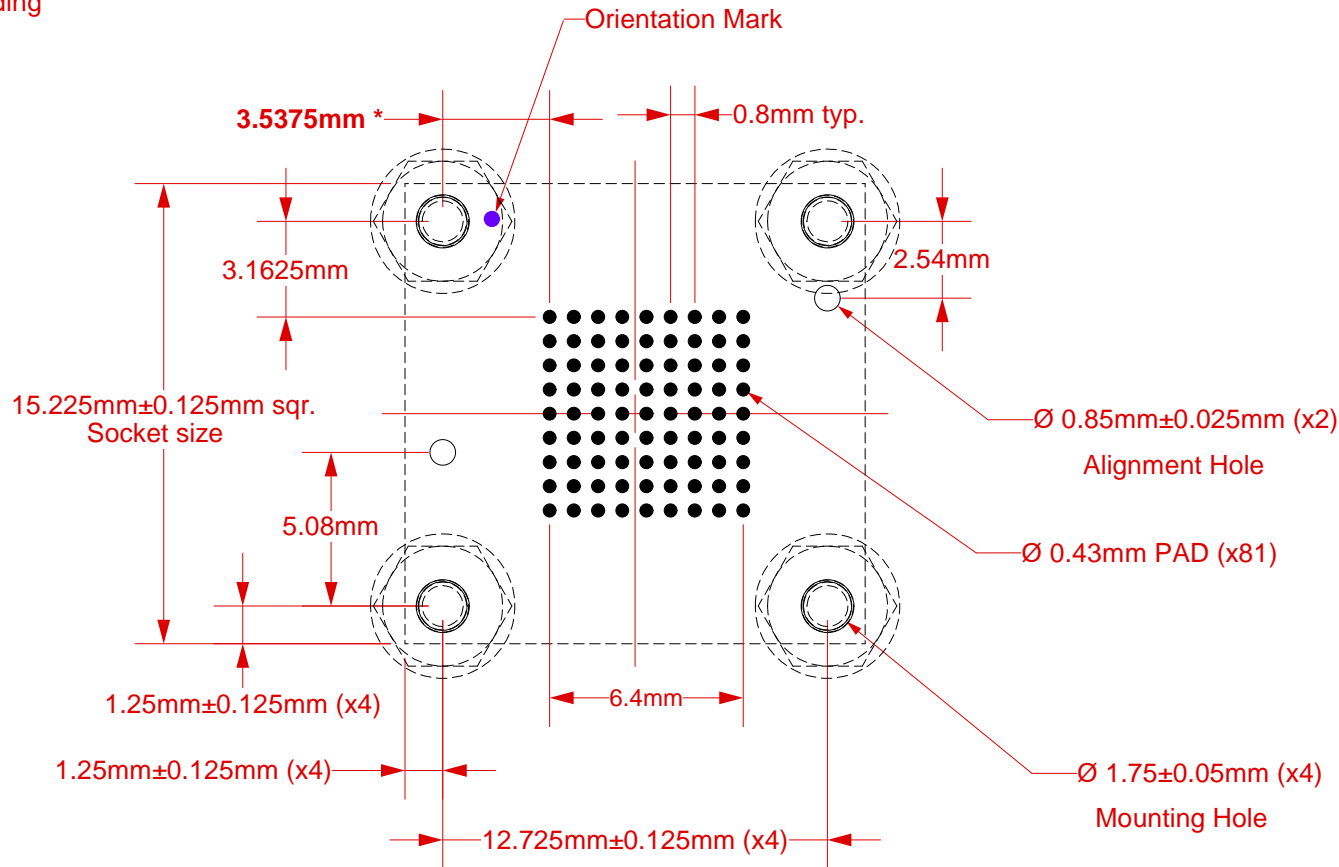
- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Ultem. Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- △ 11 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.
- △ 12 IC Guide: Torton.

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	Drawing: J. Glab		Date: 10/05/07		
	File: SG-BGA-6243 Dwg.mcd		Modified: 11/14/14, DH		

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**


Note: Full BGA pattern shown.
Please adjust pattern according to individual requirements.

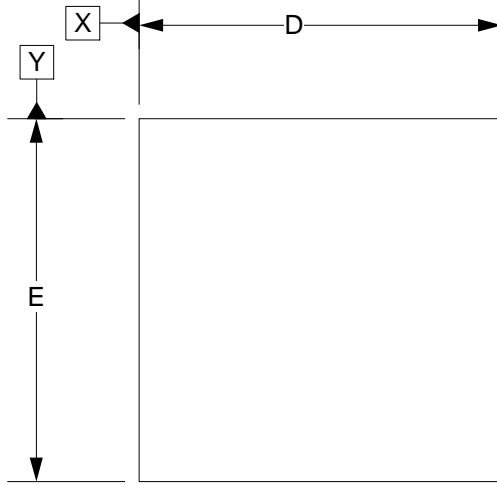


Target PCB Recommendations

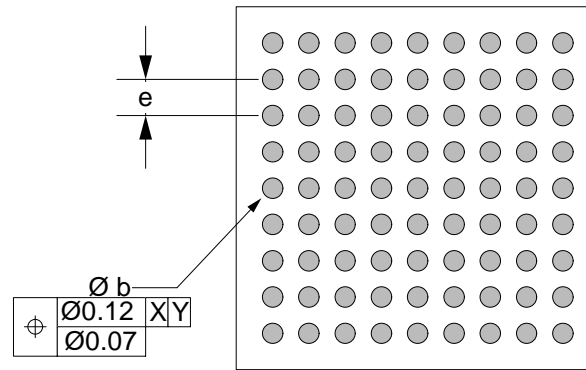
Total thickness: 2.4mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.

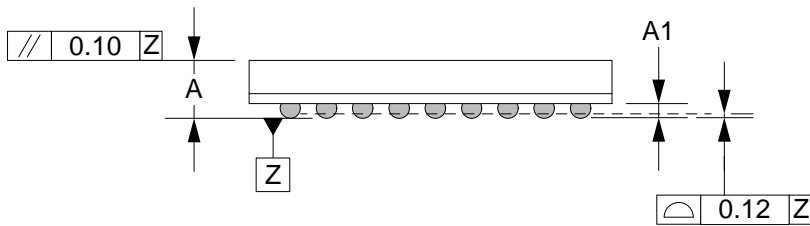
	SG-BGA-6243 Drawing	Status: Released	Scale: 4:1	Rev: C
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		File: SG-BGA-6243 Dwg.mcd	Modified: 11/14/14, DH	



Top View



Bottom View



Side View

1. Dimensions are in millimeters.
2. Interpret dimensions and tolerances per ASME Y14.5M-1994.



Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.




Datum Z (seating plane) is defined by the spherical crowns of the solder balls.



Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		1.33
A1	0.3	0.44
b	0.45	0.55
D	8.0 BSC	
E	8.0 BSC	
e	0.8 BSC	

9x9 array

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	Drawing: J. Glab		Date: 10/05/07	
	File: SG-BGA-6243 Dwg.mcd		Modified: 11/14/14, DH	